



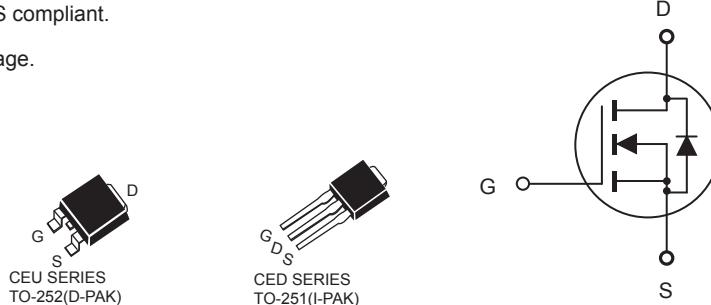
# CED55N10/CEU55N10

## N-Channel Enhancement Mode Field Effect Transistor

PRELIMINARY

### FEATURES

- 100V, 55A,  $R_{DS(ON)} = 16m\Omega$  @ $V_{GS} = 10V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handling capability.
- Lead-free plating ; RoHS compliant.
- TO-251 & TO-252 package.



### ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	55	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	220	A
Maximum Power Dissipation @ $T_C = 25^\circ C$ - Derate above $25^\circ C$	$P_D$	83.3 0.55	W W/ $^\circ C$
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 175	$^\circ C$

### Thermal Characteristics

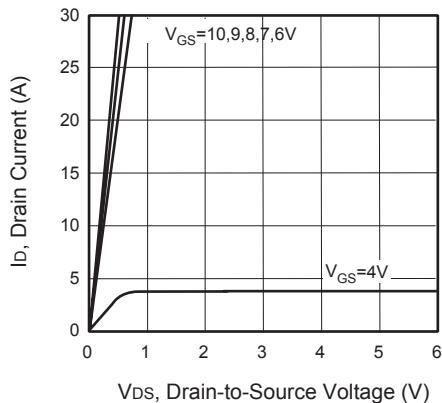
Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{JC}$	1.8	$^\circ C/W$



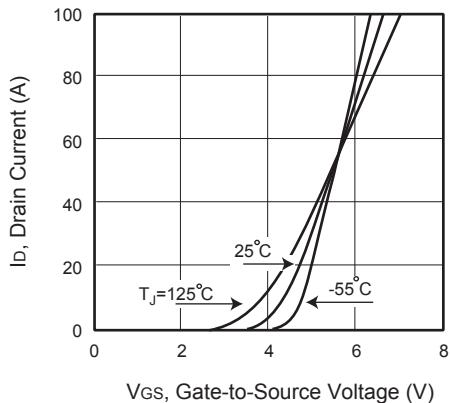
# CED55N10/CEU55N10

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

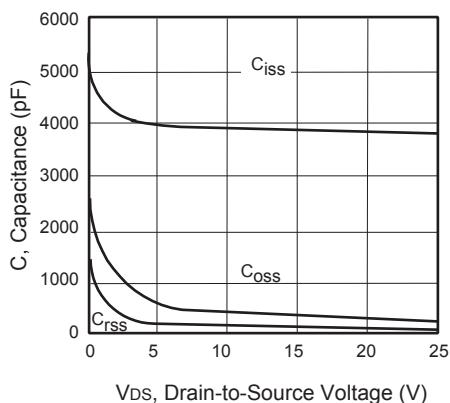
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics<sup>b</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2		4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 25\text{A}$		13	16	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>c</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		3790		pF
Output Capacitance	$C_{\text{oss}}$			240		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			140		pF
<b>Switching Characteristics<sup>c</sup></b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 50\text{V}, I_D = 30\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 5.6\Omega$		27	54	ns
Turn-On Rise Time	$t_r$			9	18	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			66	132	ns
Turn-Off Fall Time	$t_f$			12	24	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 80\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$		84	110	nC
Gate-Source Charge	$Q_{\text{gs}}$			17		nC
Gate-Drain Charge	$Q_{\text{gd}}$			19		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_S$				55	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 25\text{A}$			1.2	V
Notes : a.Repetitive Rating : Pulse width limited by maximum junction temperature b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$ . c.Guaranteed by design, not subject to production testing.						



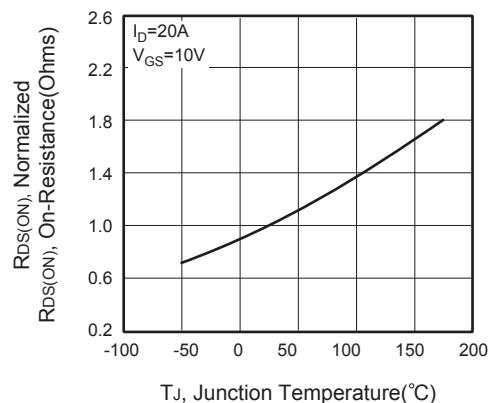
**Figure 1. Output Characteristics**



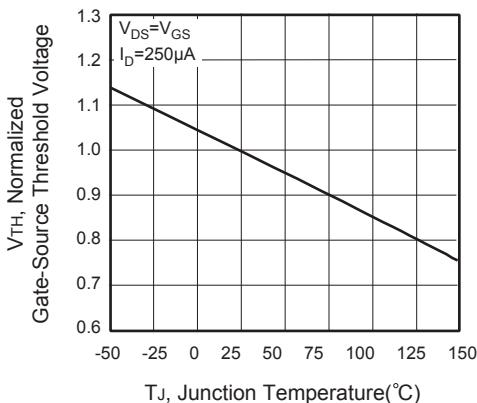
**Figure 2. Transfer Characteristics**



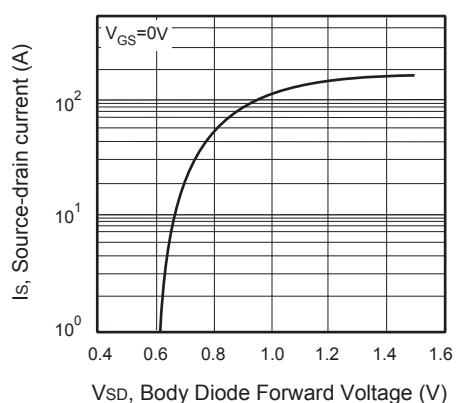
**Figure 3. Capacitance**



**Figure 4. On-Resistance Variation with Temperature**



**Figure 5. Gate Threshold Variation with Temperature**



**Figure 6. Body Diode Forward Voltage Variation with Source Current**

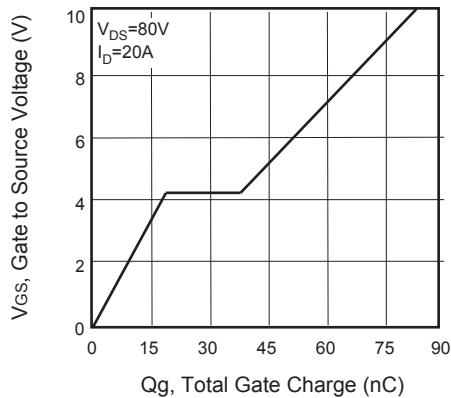


Figure 7. Gate Charge

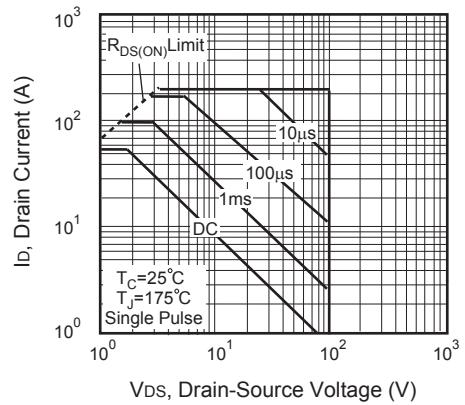


Figure 8. Maximum Safe Operating Area

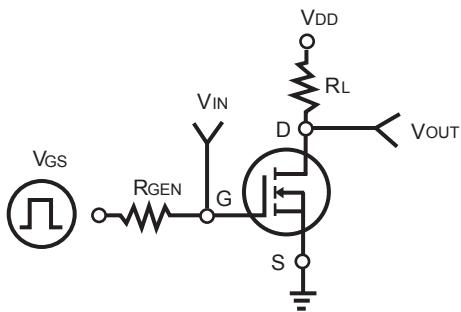


Figure 9. Switching Test Circuit

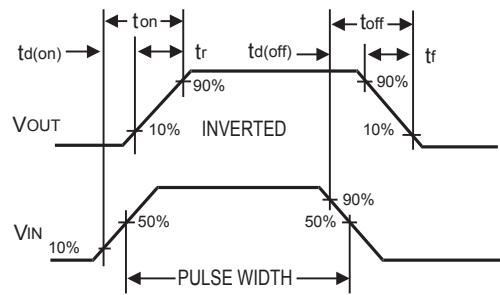


Figure 10. Switching Waveforms

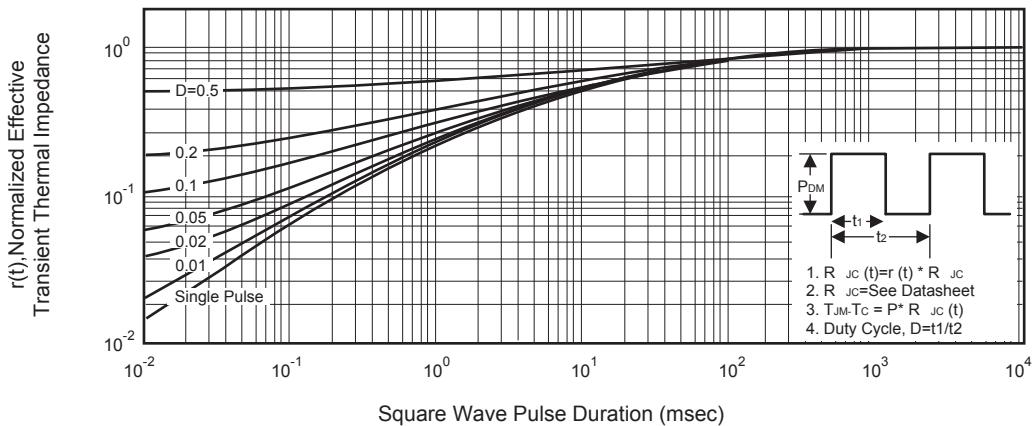


Figure 11. Normalized Thermal Transient Impedance Curve